

## In the Claims

Amend the claims as follows:

1. (Currently Amended) A printed wiring board comprising:
  - a base substrate;
  - a land conductor layer provided on said base substrate at least in part thereof;
  - an insulating layer provided on said base substrate and said land conductor layer, said insulating layer having a via hole reaching said land conductor layer, and containing glass fibers;
  - a via conducting layer covering a surface of said via hole and a surface of said insulating layer at least in the vicinity of an opening of said via hole, said via conductor layer being connected to said land conductor layer; and
  - ~~a block layer provided between the surface of said via hole and said via conductor layer for preventing migration to said via conductor layer through the glass fibers inside said insulating layer, said block layer covering the inner wall of said insulating layer at least over a range from the an upper end to the lowermost a lower end where said glass fibers inside said insulating layer exist, and the a lower end of said block layer is located spaced a physical distance away from above the surface of said land conducting layer wherein said lower end of block layer does not contact said land conducting layer.~~
2. (Original) The printed wiring board according to claim 1, wherein said insulating layer is formed by a resin layer in which the glass fibers are buried.
3. (Original) The printed wiring board according to claim 1, wherein said block layer comprises an insulating layer.
4. (Original) The printed wiring board according to claim 1, wherein said block layer comprises a resin layer.

5. (Currently Amended) A method of manufacturing a printed wiring board comprising the steps of:

(a) providing a base substrate;

(b) providing a land conductor layer on said base substrate at least in part thereof;

(c) providing an insulating layer containing glass fibers so as to cover said base substrate and said land conductor layer;

(d) providing a first via hole in said insulating layer over said land conductor layer and not contacting said land conductor layer, wherein a lower end of said first via hole is located below a lowermost portion of said glass fibers inside said insulating layer and spaced a physical distance above said land conductor layer;

(e) providing a second via hole in said first via hole, said second via hole reaching said land conductor layer, and providing a block layer on a surface of said first via hole for preventing migration through the glass fibers inside said insulating layer; and

(f) providing a via conductor layer covering a surface of said second via hole, said block layer, and a surface of said insulating layer at least in the vicinity of an opening of said first hole and connected to said land conductor layer, step (e) of providing said second via hole and said block layer including the steps of:

filling said first via hole with an insulating material; and

removing the columnar portion from the surface of said insulating material to the surface of said land conductor layer of said filled insulating material and said insulating layer between the base of said first via hole and the surface of said land conductor layer, so as to leave the insulating material of given width on the surface of said via hole.

6. (Canceled) The method according to claim 5, wherein a lower end of said first via hole is located below a lowermost portion of said glass fibers inside said insulating layer and above a surface of said land conductor layer.